

Eval Board available now:



Advantages:

- Better and Free Software availability from ARM
- Low Cost solution for Processing compared to any Leon or embedded Processors in FPGAs
- Different Operating systems possible
- Easy to use due to various experience of designers with ARM in the industrial and commercial world

RadHard ARM® Cortex® - M0 Processor

Silicon Space Technology has expanded its product portfolio to include an ARM®-based processor manufactured with the

disruptive HardSIL™ process offering superior radiation performance **>300Krad and latch-up immunity (SEL)** in extreme environments. The PA32KASA contains an embedded ARM® Cortex®-M0 processor with related peripherals supported in the Keil™ MDK-ARM Microcontroller Development Kit.



Features:

- **Manufactured with HardSIL™ technology**
- **ARM® Cortex®-M0 processor**
- **CMOS compatible input and output level, three-state bidirectional data bus**
 - 3.3 ±0.3-V I/O, 1.5 ±0.15-V Core
- **Clock rate 50MHz @ 25°C, 3.3V I/O and 1.5V Core**
- **Memory**
 - 16 KB on-chip data and 16 KB on-chip program memory
 - On-chip error detection and correction (EDAC) & scrubbing
- **Off-Chip interface to Sync Burst Memories**
 - Supports memories up to 36 Mb with EDAC
- **Peripherals**
 - Dedicated General Purpose I/O (GPIO) pins
 - Configurable direction, pull up/downs, open-drain
 - Can be used as edge or level sensitive interrupts
 - 32 General purpose counter/timers
 - Configurable interrupt sources
 - Can be trigger from 2 sources, GPIOs or other cnt/timers
 - 2 UARTs
 - Fractional baud rates, internal FIFO
 - Transmit and receive interrupt sources
 - 2 Serial Peripheral Interface (SPI) controllers
 - Configurable clock frequency, internal FIFO
 - Multiple chip select outputs
- **System-level Triple Mode Redundancy (TMR) on all internal registers**
- **Radiation hardening performance¹**
 - Manufactured with HardSIL™ for superior RH by process performance.
 - TID > 300Krad (Si)
 - Soft error rate (SER): Testing results in Q1/2014
 - Latch up immunity > LET = 110 MeV-cm²/mg (T=125oC)
- **Packaging**
 - 188 pin, ceramic QFP
 - Package footprint of 1.3" x 1.3"
 - 25 mil lead pitch

